

# Product End-of-Life Disassembly Instructions

**Product Name / Model:** DT Research Rugged Tablet / DT313Y

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of DT Research products to remove components and materials requiring selective treatment, as defined by EU Directive 2012/19/EU of the European Parliament and of the Council of 4 July 2012 on waste electrical and electronic equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards Assemblies (PCBA)	With a surface greater than 10 sq cm	1
Mass storage device	Permanently soldered to PCBA	0
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches,	0
LCD Display	a surface greater than 100 sq cm includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and	Include the cartridges, print heads, tubes, vent chambers, and service	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 SCREW DRIVER(Plum flower head)	
Description #2 HAIR DRYER	
Description #3 KNIFE BLADE	

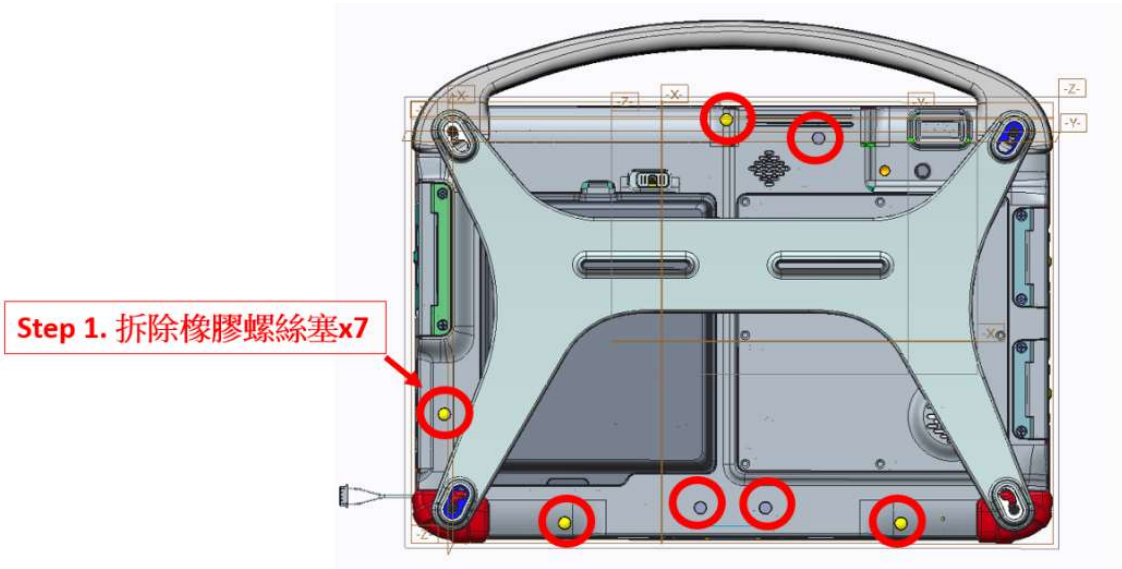
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

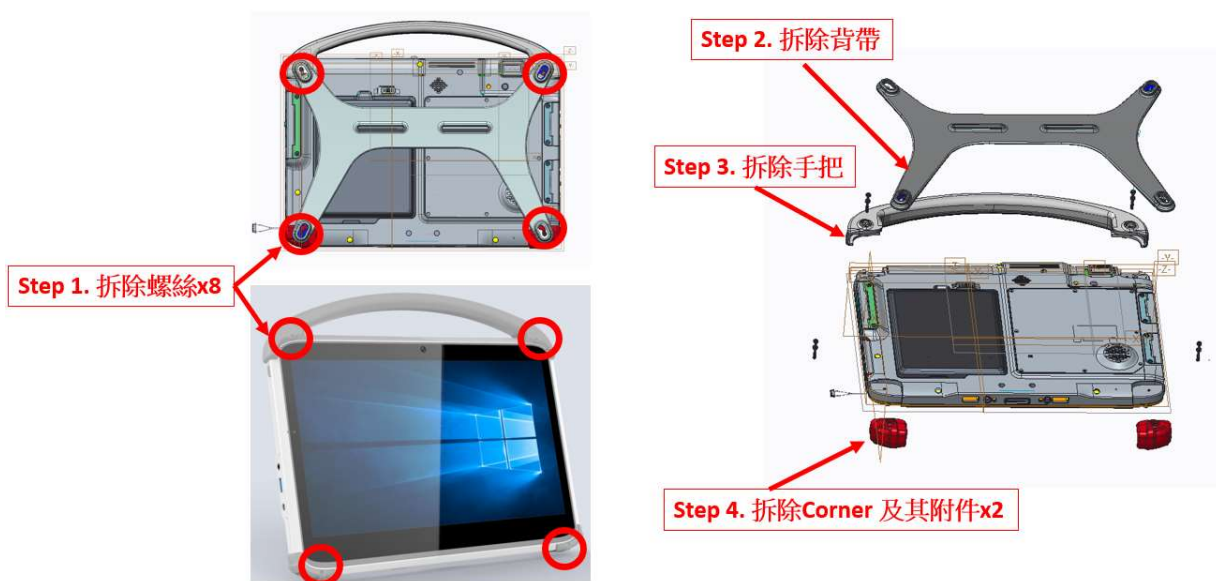
1. Dismantle the system.
2. Dismantle the back enclosure.
3. Dismantle the back cover.
4. Dismantle the I/O door.
5. Dismantle the PCBA screws and disconnect the connectors.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

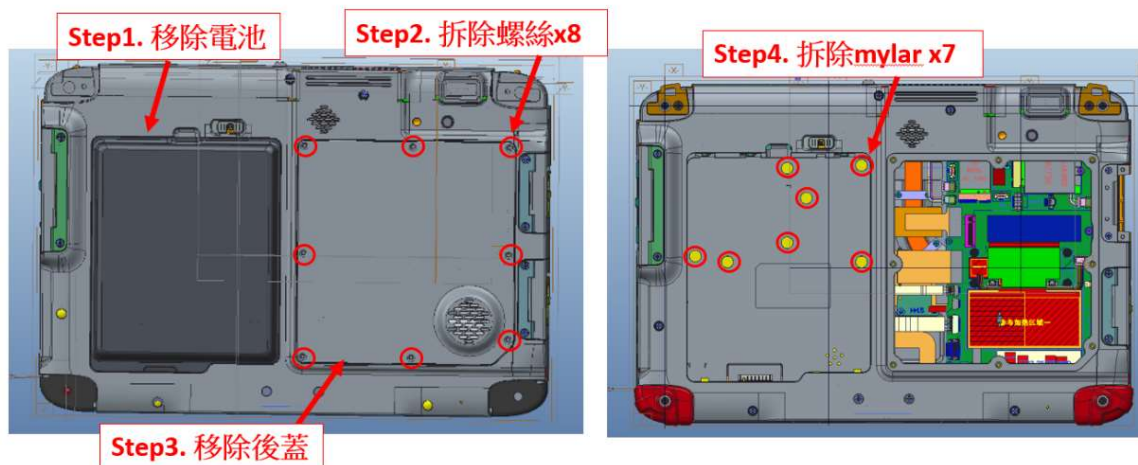
- (1) Dismantle the system
- (a) Dismantle the silicone hole plug



(b) Dismantle the hand strap, handle and corners.

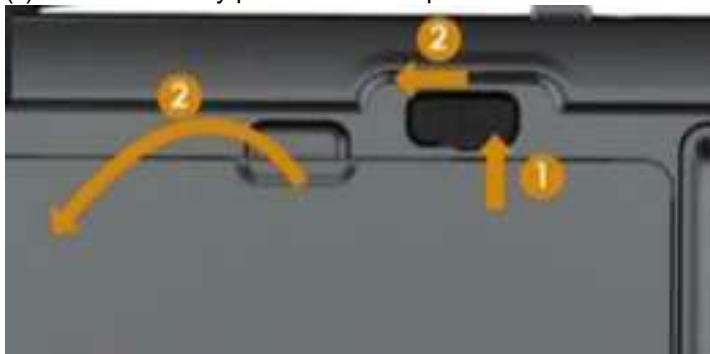


(c) Remove batter pack and back cover

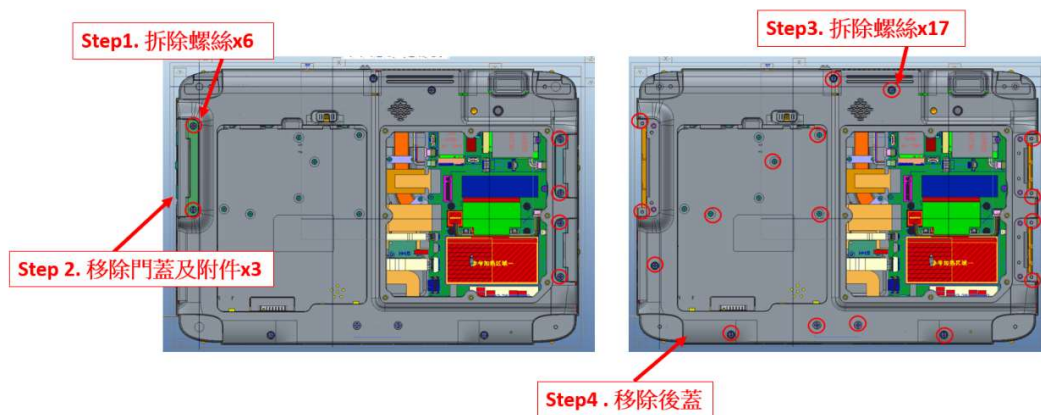


\*\* Detailed steps for removing battery pack

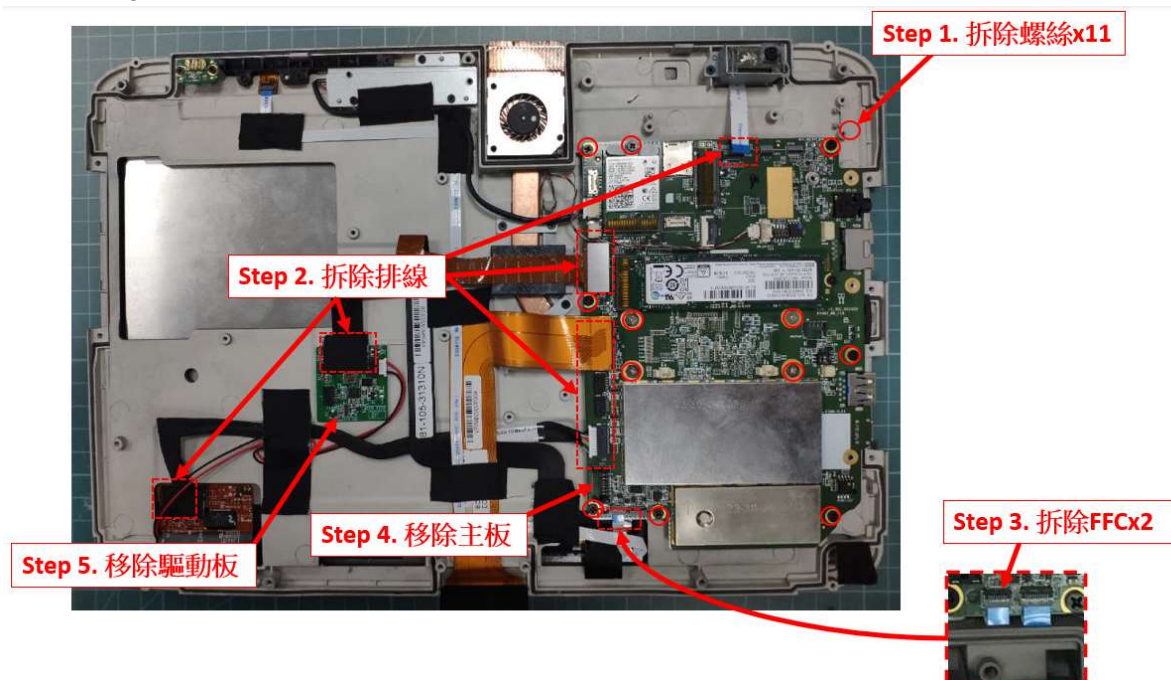
- (i) Slide the battery latch to the unlocked position.
- (ii) Lift the battery pack off the compartment.



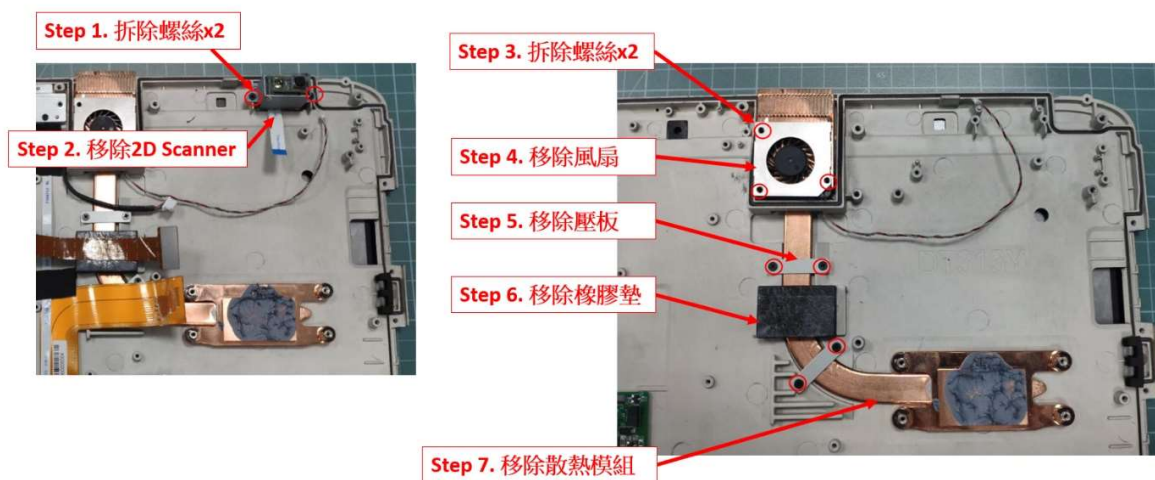
(d) Remove the I/O door and back enclosure



(e) Remove PCBA



(f) Remove DC fan and thermal module

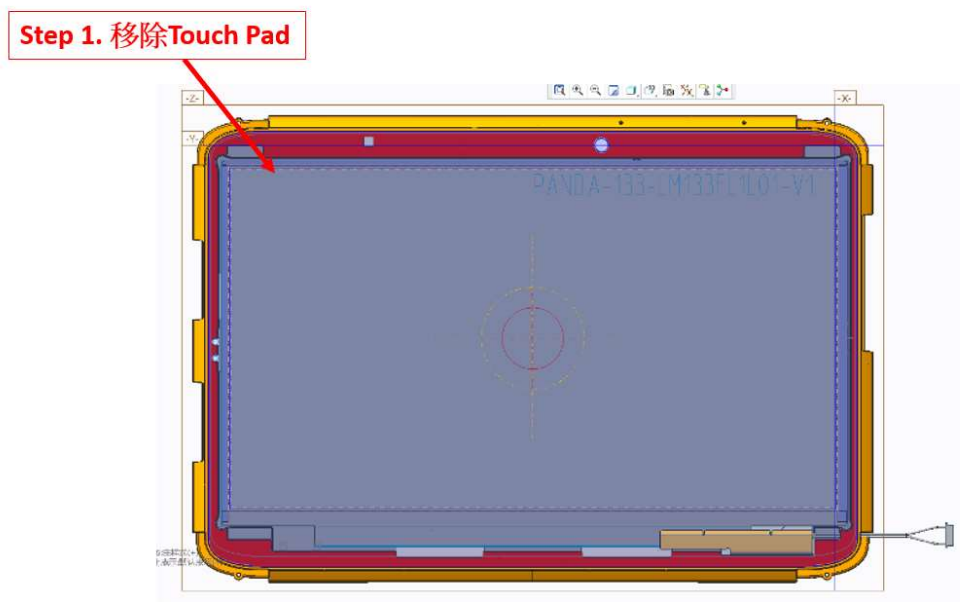




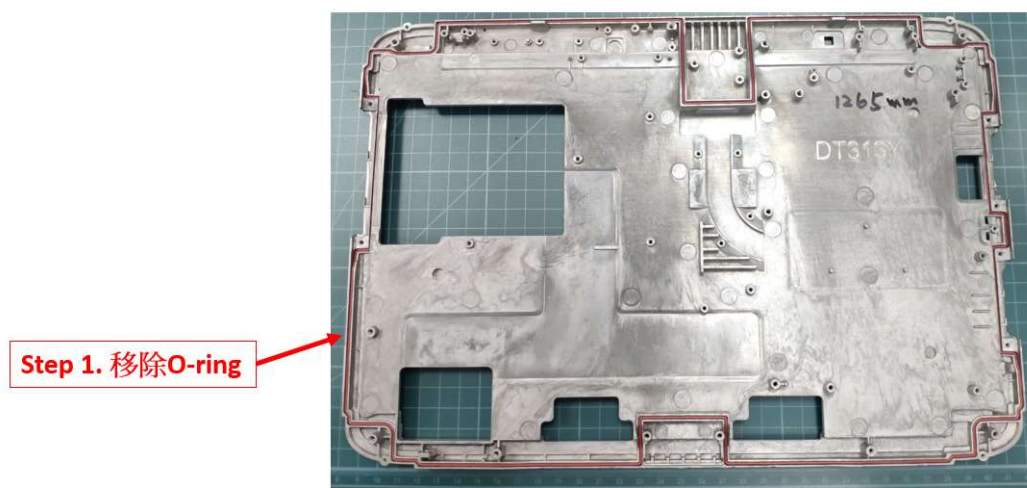
(g) Remove camera module and speaker



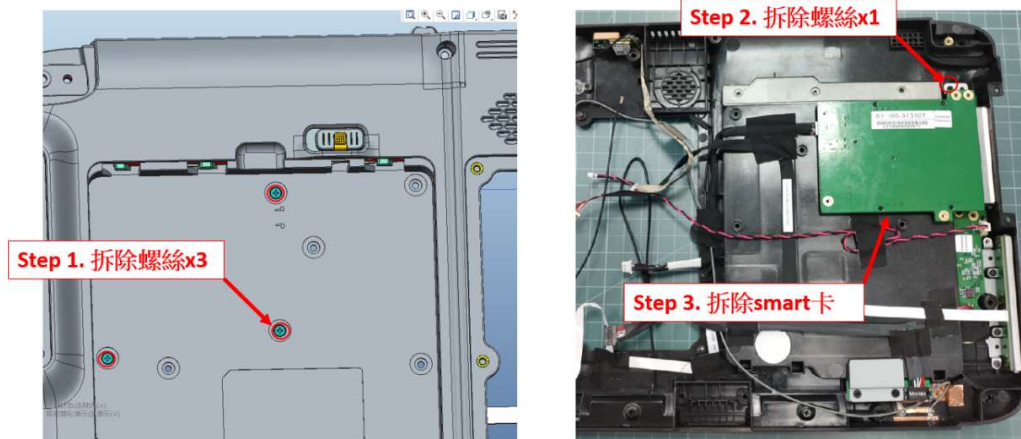
(h) Remove LCD Panel



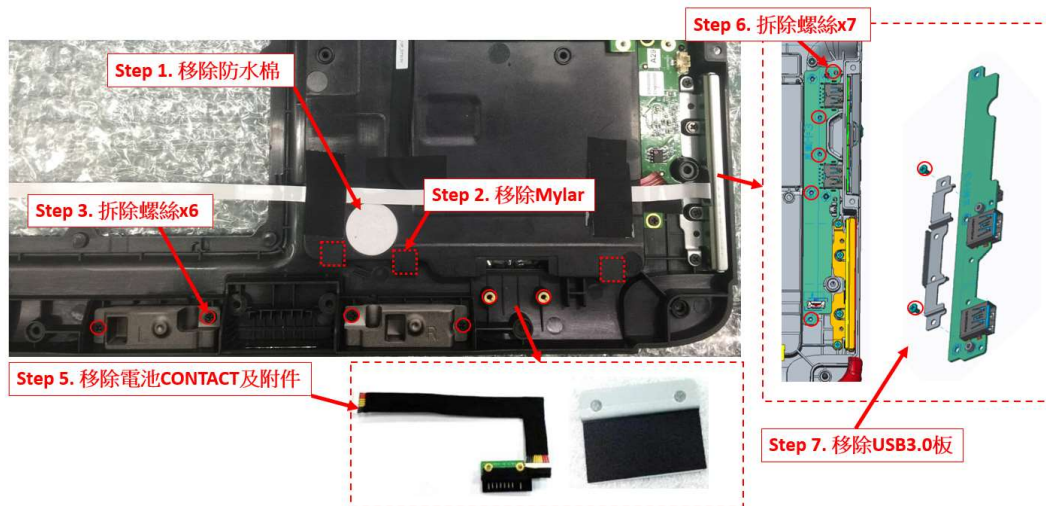
(i) Remove water-proof parts (O-ring)



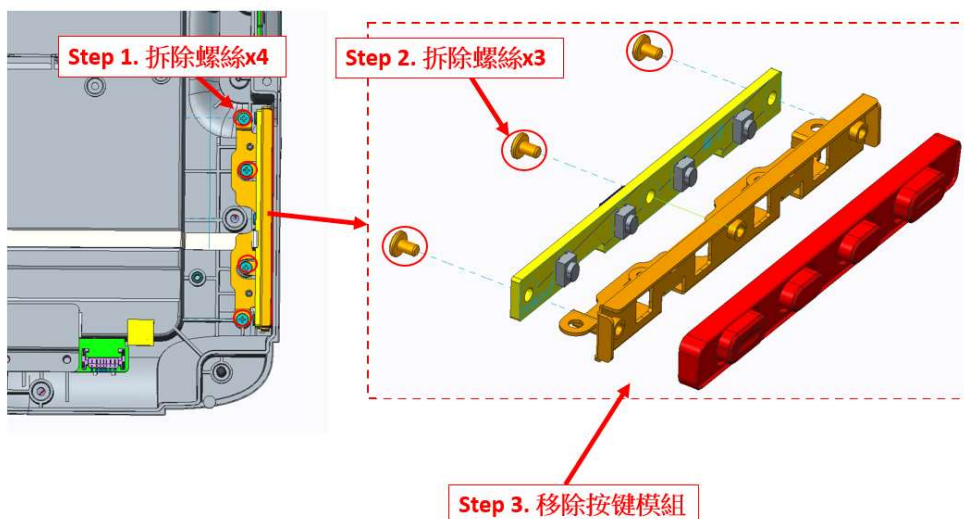
- (2) Dismantle the back enclosure  
(a) Remove smart card



- (b) Remove USB connectors



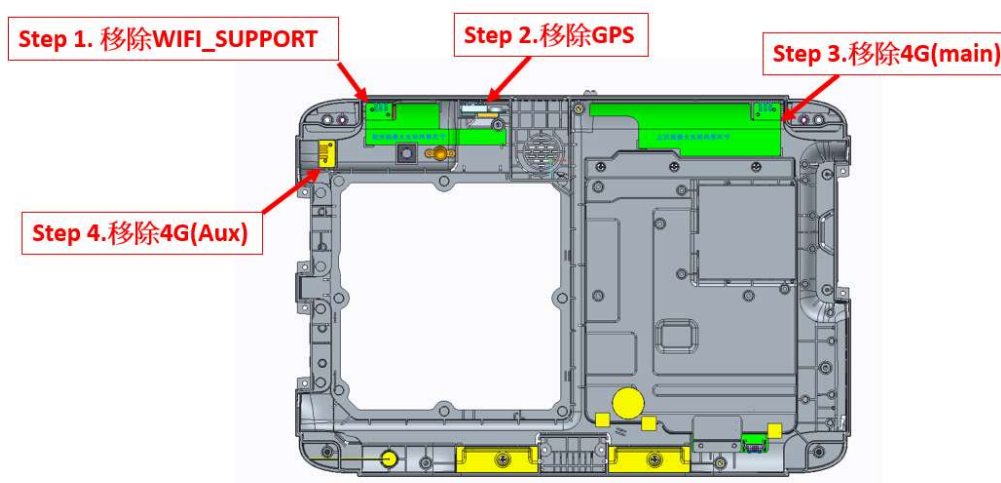
- (c) Remove buttons module



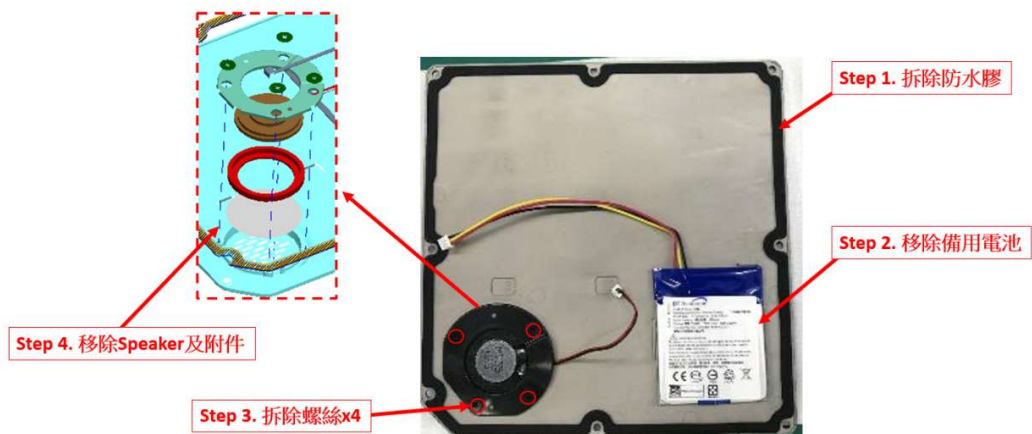
(d) Dismantle mechanism of battery pack



(e) Remove the antennas



(3) Dismantle the back cover





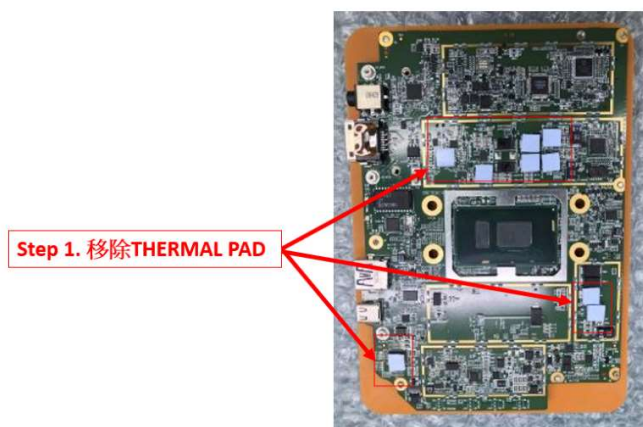
(4) Dismantle the I/O door



(5) Dismantle the PCBA screws and disconnect the connectors  
(a) Bottom side of PCBA - Remove Gaskets and Shieldings



(b) Bottom side of PCBA – Remove thermal pad





(c) Top side of PCBA – Remove shielding and thermal pad.

